

Data sheet Product ICK BGA 10 x 10 x 10



Heatsinks and active heatsinks for processors>Heatsinks for BGAs

10 x 10 x 10 mm, for IC design BGA and others

Features

way of fixation:	• therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	10 mm
height:	10 mm
plate thickness:	1.8 mm
length:	10 mm
thermal resistance:	28.5 - 9.1 K/W
dissipation loss:	1.9 W
surface:	black anodised

Technical Drawing

